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FORM PTO-1595 U.S. Department

*MRD 5-21-98*  
Attorney Docket No.: TII-22346



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To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

<p>1. Name of conveying party(ies):</p> <p>1) Yutaka Komai 2) Texas Instruments Japan, Ltd.</p>	<p>2. Name and Address of receiving party(ies): Name: Texas Instruments Incorporated Address: P.O. Box 655474, MS 3999 City: Dallas, Texas State: TX Zip: 75265</p> <p>Additional name(s) &amp; address(es) attached? ___ Yes <u>X</u> No</p>
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3. Nature of Conveyance:

\_\_\_ X \_\_\_ Assignment \_\_\_ Merger  
 \_\_\_ Security Agreement \_\_\_ Change of Name  
 \_\_\_ Change of Address

Execution Date: April 24, 1998

4. Application number(s) or patent number(s).  
 \_\_\_ This document is being filed together with a new application.

Execution date of the application: April 21, 1998

Title: FUSE FOR SEMICONDUCTOR DEVICE AND SEMICONDUCTOR DEVICE

Docket No: TII-22346

<p>A. Patent Application No.(s): <u>S.N. 08/984,012</u></p> <p>Additional numbers attached? ___ Yes <u>X</u> No</p>	<p>B. Patent No.(s)</p> <p>Additional numbers attached? ___ Yes <u>X</u> No</p>
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<p>5. Name and address of party to whom correspondence concerning document should be mailed:</p> <p>Name: William B. Kempler, Reg. No. 28,228 Senior Corporate Patent Counsel Texas Instruments Incorporated</p> <p>Address: P.O. Box 655474, MS 3999 City: Dallas State: TX Zip: 75265</p>	<p>6. Number of applications and patents involved: <u>(1)</u></p>
	<p>7. Amount of fee enclosed or authorized to be charged: <u>\$40</u></p>
	<p>8. Deposit Account No: <u>20-0668</u> (Duplicate copies not required).</p>

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9. Statement and signature:

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

05/27/1998 **IMNES** 00000011 08984012

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*William B. Kempler* \_\_\_\_\_ May 15, 1998  
 William B. Kempler, Reg. No. 28,228 Date

## ASSIGNMENT

**WHEREAS, TEXAS INSTRUMENTS JAPAN, LTD.** (hereinafter **TIJ**), a Japanese company having its headquarters at Aoyama Fuji Bldg., 6-12 Kita-Aoyama 3-Chome, Minato-ku, Tokyo, Japan, under the laws of Japan made application, in its own name, for Letters Patent in Japan in respect of an invention as set forth below;

**WHEREAS**, the or each below named inventor (hereinafter **INVENTOR**) is the or an inventor of the said invention;

**WHEREAS, TEXAS INSTRUMENTS INCORPORATED**, a corporation organized and existing under the laws of the State of Delaware, with its principal office at 13510 North Central Expressway, Dallas, Texas 75243, is desirous of acquiring our entire right, title and interest in and to the said invention outside of Japan, and in and to the U.S. patent application as identified hereinafter and any Letters Patent that may issue thereon;

**NOW, THEREFORE**, for good and valuable consideration, the receipt of which is hereby acknowledged, by this Assignment, **TIJ** and **INVENTOR** sell and assign to the said **TEXAS INSTRUMENTS INCORPORATED**, its successors and assigns, the entire right, title and interest in and to the said invention in the U.S.A. and all other countries outside Japan; in and to the U.S. patent application as identified below and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and the right to file applications and obtain patents in its own name in any said other country or group of countries, and to claim priority under the terms of the International Convention for the Protection of Industrial Property or any other relevant convention;

**TIJ** and **INVENTOR** hereby authorize and request the Commissioner of Patents to issue U.S. patents for said invention, or U.S. patents resulting therefrom, insofar as the interest of **TIJ** and **INVENTOR** is concerned to the said **TEXAS INSTRUMENTS INCORPORATED**, as assignee of the entire right, title and interest.

**TIJ** and **INVENTOR** further agree to communicate to **TEXAS INSTRUMENTS INCORPORATED** or to its successors, assigns and legal representatives, any facts known to **TIJ** and **INVENTOR** respecting the said invention, and at the expense of **TEXAS INSTRUMENTS INCORPORATED**, sign any and all patent applications, assignments, affidavits and other lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, testify in any legal or quasi-legal proceedings and generally do everything possible to aid said **TEXAS INSTRUMENTS INCORPORATED**, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries outside of Japan.

FUSE FOR SEMICONDUCTOR DEVICE AND SEMICONDUCTOR DEVICE  
Title of Invention

Yutaka Komai  
Inventor

Japanese Application No.: 8(1996)-337582 Filed: December 3, 1996

U.S. Application Serial No.: 08/984,012 Filed: December 3, 1997

**IN WITNESS WHEREOF**, this Agreement has been executed  
as set forth below;

Signed at Tokyo, Japan on April 24, 1998

by **Texas Instruments Japan, Ltd.**


Name   
Toshiki Ikoma

Title Representative Director and President

Date 4/24/98

and by the **INVENTOR(S)**:

Inventor: Yutaka Komai

Signature: 

Address: 1871-43, Nakamutamishine, Tsuchiuta-city  
Ibaraki, Japan 300-0842

Date Apr 21 98